

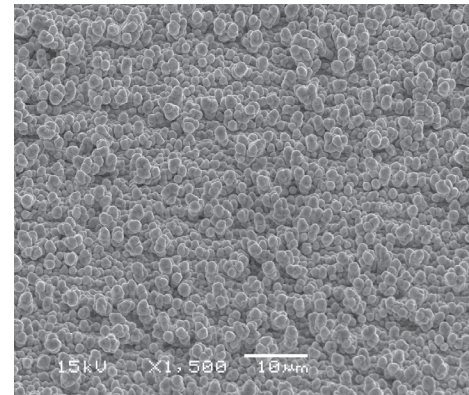
High temperature stability, double treat, electrodeposited copper foil.

Applications:

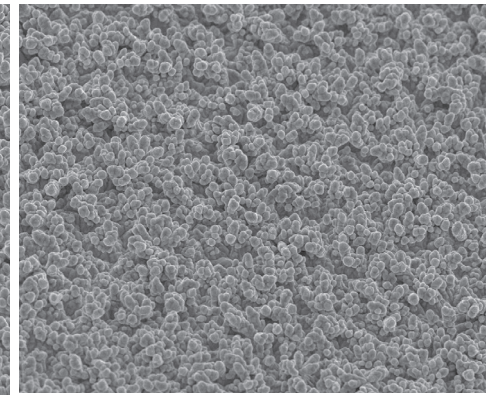
- PCB inner layers

Features:

- IPC Grade III
- Treatment on both sides of foil
- High temperature lamination compatible



Treated Drum Side
H oz. /18 µm (1500x)



Treated Matte Side
H oz. /18 µm (1500x)

Typical Values:

Attribute		Unit	Value					Reference	
Thickness Designation			Q	T	H	1	2	3	
Nominal Thickness		µm	9	12	18	35	70	103	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
		oz.	1/4	3/8	1/2	1	2	3	
Area Weight		g/m ²	75.9	106.8	152.5	305	610	915	
		g/254 in ²	12.5	17.5	25	50	100	150	
		oz./ft ²	0.25	0.375	0.5	1	2	3	
Roughness	Drum Side Ra	µm			4.06	4.06	4.06		IPC-TM-650-2.2.17
		µ"			160	160	160		
	Matte Side Rz	µm			5.08	6.35	10.16		
		µ"			200	250	400		
Tensile	Ambient	Kg/mm ²			42.2	38.7	36.9		IPC-TM-650-2.4.18
		Kpsi			60	55	52.5		
	180°C	Kg/mm ²			21.1	21.1	21.1		
		Kpsi			30	30	30		
Elongation	Ambient	%			8	15	20		
	180°C	%			8	8	8		
Peel Strength* (Drum/Treated Side)	Cond. B	Kg/cm			0.98	1.16	1.25		IPC-TM-650-2.4.8
		Lbs/in			5.5	6.5	7.0		

* Peel strength measured on 170°C Tg Epoxy

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